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Data sheet

BAW filter WLAN 2G

Series/type: B8857 Ordering code: B39242B8857L210 Date: February 13, 2019 Version: 2.2

DCN: 80-PA243-60 Rev. C

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1 Application

- Premium-performance low-loss BAW RF single filter for Bluetooth/WLAN with LTE Band 7 / Band 40 / Band 41 coexistence
- Usable pass band 79.0 MHz
- Unbalanced to unbalanced operation
- Filter impedance 50 Ω
- High out of band selectivity
- Excellent insertion loss

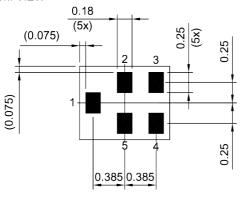
2 Features

- Package size 1.1 mm × 0.9 mm
- Package height 0.7 mm
- Approximate weight 1 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

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3 Package

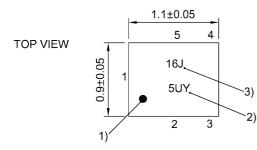
BOTTOM VIEW



Pad and pitch tolerance ±0.05

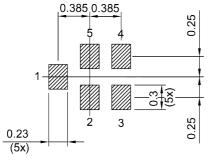
SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number





Landing pad tolerance -0.02 **Figure 1:** Drawing of package with encoded number ###=8MS (for B8857) and package height A = 0.7 mm (max.). See Sec. Package information (p. 19).

4 Pin configuration

- 1 Input (to PA (unbalanced))
- 4 Output (to ANT (unbalanced))
- 2, 3, 5 Ground

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5 Matching circuit

■ *L*_{p4} = 12 nH

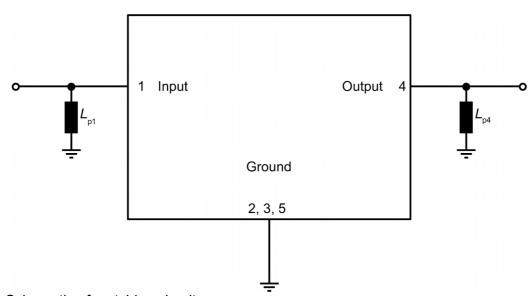


Figure 2: Schematic of matching circuit.

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6 Characteristics

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Temperature range for specification
Input terminating impedance
Output terminating impedance

 $\begin{array}{ll} T_{\rm SPEC} & = -30 \ ^{\circ}{\rm C} \ \dots +85 \ ^{\circ}{\rm C} \\ Z_{\rm IN} & = 50 \ \Omega \ // \ 12 \ \rm nH^{1)} \\ Z_{\rm OUT} & = 50 \ \Omega \ // \ 12 \ \rm nH^{1)} \end{array}$

Characteristics				min. for $T_{_{\rm SPEC}}$	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
Center frequency			f _c		2442		MHz
Insertion loss – WLAN			α				
Channel 1	2403.1 2420.9	MHz		_	1.6 ²⁾	2.4 ²⁾	dB
Channel 2	2408.1 2425.9	MHz		_	1.4 ²⁾	2.0 ²⁾	dB
Channel 3-10	2413.1 2465.9	MHz		_	1.3 ²⁾	1.8 ²⁾	dB
Channel 11	2453.1 2470.9	MHz		_	1.3 ²⁾	1.8 ²⁾	dB
Channel 12	2458.1 2475.9	MHz		_	1.4 ²⁾	2.0 ²⁾	dB
Channel 13	2463.1 2480.9	MHz		_	1.6 ²⁾	2.5 ²⁾	dB
Amplitude ripple (p-p)			Δα				
Channel 1	2403.1 2420.9	MHz		—	1.0	2.6 ³⁾	dB
Channel 2	2408.1 2425.9	MHz		_	0.6	2.0	dB
Channel 3	2413.1 2430.9	MHz		_	0.6	1.5	dB
Channel 4-10	2418.1 2465.9	MHz		—	0.5	1.5	dB
Channel 11	2453.1 2470.9	MHz		_	0.6	1.7	dB
Channel 12	2458.1 2475.9	MHz		_	0.7	2.0	dB
Channel 13	2463.1 2480.9	MHz		_	1.3	2.7 ⁴⁾	dB
VSWR			VSWR				
@ input port	2403.1 2420.9	MHz		—	1.3	2.3 ⁵⁾	
	2420.9 2480.9	MHz		_	1.5	2.3	
@ output port	2403.1 2420.9	MHz		_	1.3	2.3 ⁵⁾	
	2420.9 2480.9	MHz			1.6	2.3	
Attenuation			α				
	100 1805	MHz		31	35	—	dB
	1805 2170	MHz		33	37	—	dB
	2300 2360	MHz		45 ⁶⁾	52 ⁶⁾	—	dB
	2360 2365	MHz		44 ⁶⁾	53 ⁶⁾	—	dB
	2365 2370	MHz		44 ⁶⁾	50 ⁶⁾	—	dB
	2370 2380	MHz		32 ⁶⁾	49 ⁶⁾	_	dB
	2496 2501	MHz		19 ^{3), 6)}	43 ⁶⁾		dB
	2500 2505	MHz		45 ^{3), 6)}	64 ⁶⁾	—	dB
	2505 2550	MHz		45 ⁶⁾	49 ⁶⁾		dB
	2550 2570	MHz		42 ⁶⁾	46 ⁶⁾	—	dB
	2570 2620	MHz		40 ⁶⁾	44 ⁶⁾	—	dB
	2620 2690	MHz		39 ⁶⁾	43 ⁶⁾	—	dB
	4800 5805	MHz		25	33	—	dB
	7200 7500	MHz		20	34	—	dB

¹⁾ See Sec. Matching circuit (p. 6).



- ²⁾ Averaged value within each Wifi channel width of 17.8 MHz.
- ³⁾ +25°C to +85°C.
- ⁴⁾ +25°C.
- ⁵⁾ +10°C to +85°C.
- ⁶⁾ Averaged values of linear S-parameter over any 5 MHz.

7 **Maximum ratings**

Storage temperature	$T_{\rm STG}^{1)} = -40 ^{\circ}{\rm C} \dots +90 ^{\circ}{\rm C}$	
DC voltage	$ V_{\rm DC} = 5.0 \rm V^{5)}$	
ESD voltage		
	V _{ESD} ²⁾ = 275 V	Machine model.
	V _{ESD} ³⁾ = 325 V	Human body model.
	V _{ESD} ⁴⁾ = 700 V	Charged device model.
Input power @ input port: 2403.1 2480.9 MHz (WLAN channel 1 to channel 13)	$P_{\rm IN} = 25 \rm dBm$	19 MHz WLAN signal for 5000 h @ 65 °C.

1) Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

2) According to JESD22-A115B (MM - Machine Model), 10 negative & 10 positive pulses.

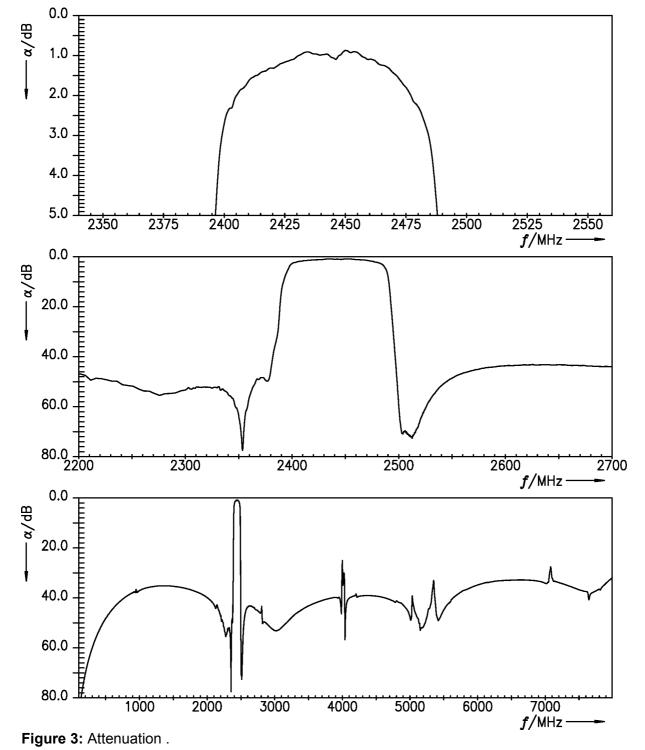
3)

According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse. According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses. 4)

5) 168h Damp Heat Steady State acc. to IEC60068-2-67 Cy. RF360 Europe GmbH A Qualcomm – TDK Joint Venture

8 Transmission coefficient

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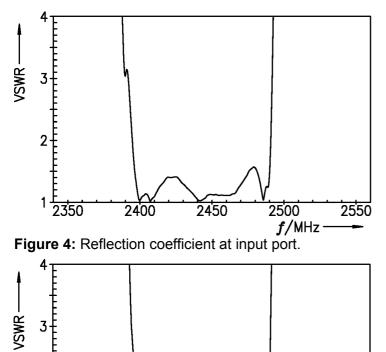
9 Reflection coefficients

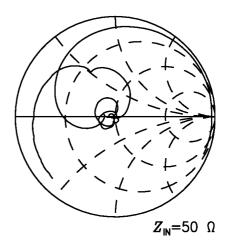
2

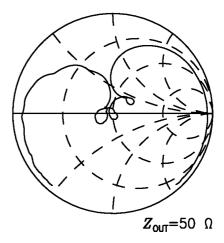
1

2350

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2550

2500

Figure 5: Reflection coefficient at output port.

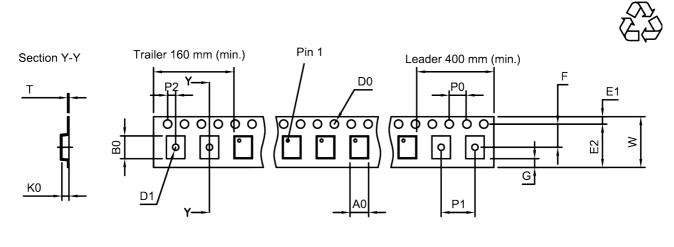
2450

2400



10 Packing material

10.1 Tape



User direction of unreeling

Figure 6: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

 $\begin{array}{c|c} A_0 & 1.1{\scriptstyle\pm 0.05} \text{ mm} \\ \hline B_0 & 1.3{\scriptstyle\pm 0.05} \text{ mm} \\ \hline D_0 & 1.5{\scriptstyle\pm 0.1/{-0}} \text{ mm} \\ \hline D_1 & 0.4{\scriptstyle\pm 0.05} \text{ mm} \\ \hline E_1 & 1.75{\scriptstyle\pm 0.1} \text{ mm} \end{array}$

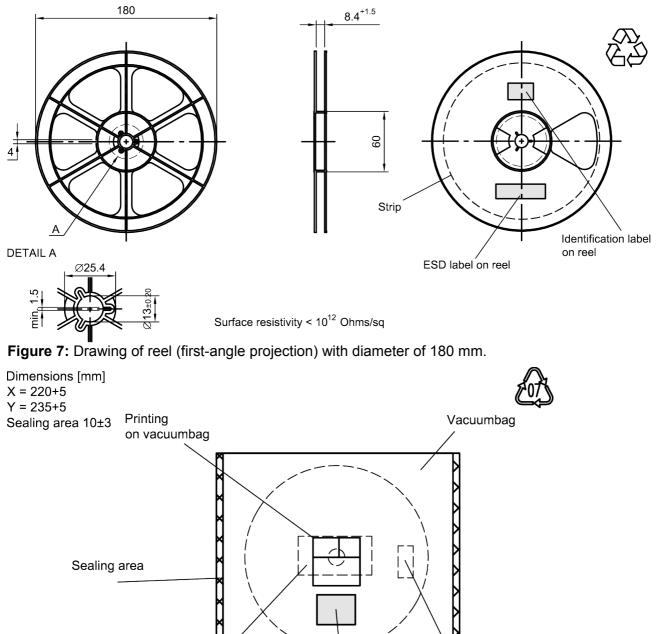
E2	-
F	3.5±0.05 mm
G	-
K ₀	0.76±0.03 mm
P ₀	4.0±0.1 mm

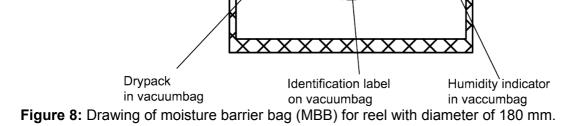
P ₁	2.0±0.1 mm
P ₂	2.0±0.05 mm
Т	0.25±0.03 mm
W	8.0±0.1 mm

Table 1: Tape dimensions.



10.2 Reel with diameter of 180 mm





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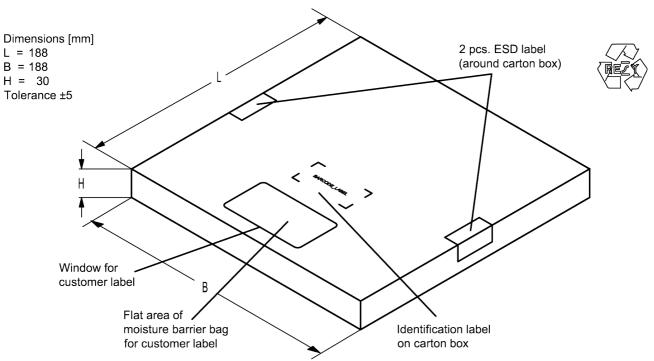


Figure 9: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

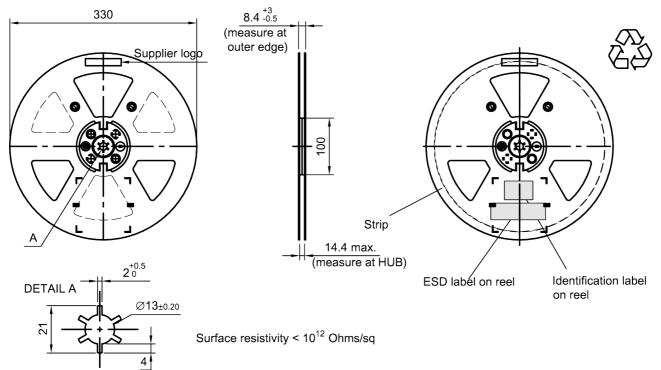


Figure 10: Drawing of reel (first-angle projection) with diameter of 330 mm.



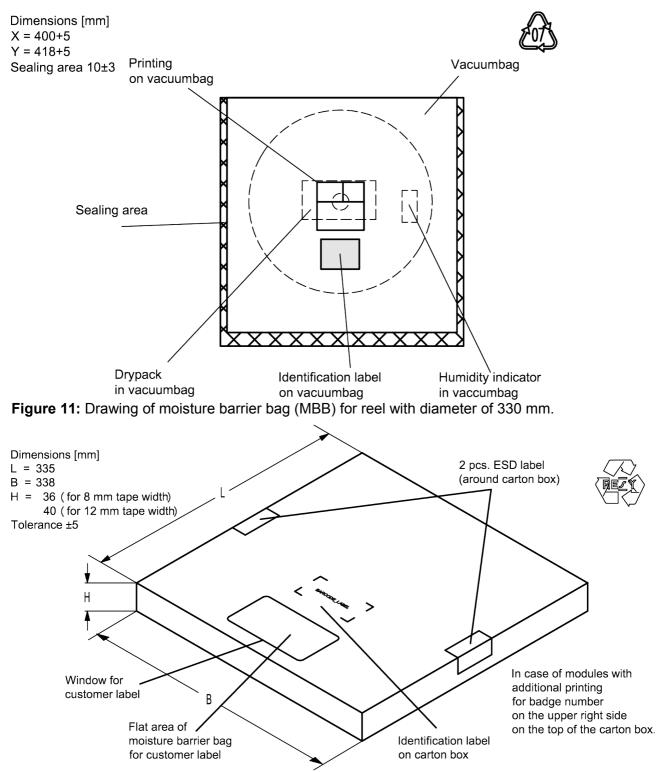


Figure 12: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number is encoded by a special	of the ordering code, BASE32 code into a 3 digit marking.	e.g., B3xxxxB <u>1234</u> xxxx,
Example of decoding 16J	type number marking on device =>	in decimal code. 1234
	32 ¹ + 18 (=J) x 32 ⁰ = oduct type B8857 is 8MS.	1234

■ Lot number:

The last 5 digits of the lot number, 12345, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device **5UY**

decoding lot number marking on device		in decimal code.
5UY	=>	12345
5 x 47 ² + 27 (=U) x 47 ¹ + 31 (=Y) x 47 ⁰	=	12345

Adopted BASE32 code for type number			
Decimal	Base32	Decimal	Base32
value	code	value	code
0	0	16	G
1	1	17	Н
2	2	18	J
3	3	19	К
4	4	20	М
5	5	21	N
6	6	22	Р
7	7	23	Q
8	8	24	R
9	9	25	S
10	А	26	Т
11	В	27	V
12	С	28	W
13	D	29	Х
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	Т
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	В	35	f
12	С	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	Н	41	١
18	J	42	?
19	K	43	{
20	L	44	}
21	М	45	<
22	N	46	>
23	Р		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
<i>T</i> > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
<i>T</i> > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T _{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

 Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

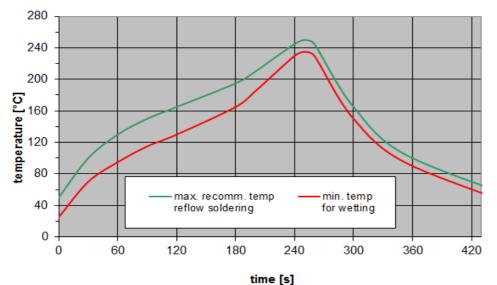


Figure 13: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Ordering codes and packing units

Ordering code	Packing unit
B39242B8857L210	15000 pcs
B39242B8857L210S 5	5000 pcs

Table 4: Ordering codes and packing units.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <u>www.rf360jv.com/orderingcodes</u>.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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